# MA3J745D, MA3J745E (MA745WA, MA745WK)

## Silicon epitaxial planar type

### For switching

### ■ Features

- Two elements are contained in one package, allowing highdensity mounting
- Low forward voltage V<sub>F</sub> , optimum for low voltage rectification
- Optimum for high frequency rectification because of its short reverse recovery time (t<sub>rr</sub>)
- S-Mini type 3-pin package

### ■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter		Symbol	Rating	Unit
Reverse voltage (DC)		$V_R$	30	V
Peak reverse voltage		$V_{RM}$	30	V
Forward current (DC)	Single	$I_F$	30	mA
	Double *		20	
Peak forward current	Single	$I_{FM}$	150	mA
	Double *		110	
Junction temperature		T <sub>j</sub>	125	°C
Storage temperature		$T_{stg}$	-55 to +125	°C

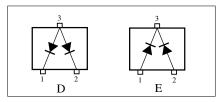
Note) \* : Value per chip

# Unit: mm 0.3\(\frac{40.1}{0.05}\) \[ \begin{array}{c} \b

### Marking Symbol

• MA3J745D: M3E • MA3J745E: M3D

### Internal Connection



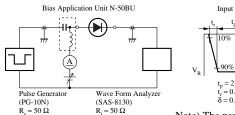
# ■ Electrical Characteristics $T_a = 25$ °C

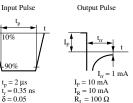
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Reverse current (DC)	$I_R$	$V_R = 30 \text{ V}$			30	μΑ
Forward voltage (DC)	$V_{F1}$	$I_F = 1 \text{ mA}$			0.3	V
	$V_{F2}$	$I_F = 30 \text{ mA}$			1.0	
Terminal capacitance	C <sub>t</sub>	$V_R = 1 \text{ V, } f = 1 \text{ MHz}$		1.5		pF
Reverse recovery time *	t <sub>rr</sub>	$I_F = I_R = 10 \text{ mA}$		1.0		ns
		$I_{rr} = 1 \text{ mA}, R_L = 100 \Omega$				
Detection efficiency	η	$V_{in} = 3 V_{(peak)}, f = 30 MHz$		65		%
		$R_L = 3.9 \text{ k}\Omega, C_L = 10 \text{ pF}$				

Note) 1. This product is sensitive to electric shock (static electricity, etc.). Due attention must be paid on the charge of a human body and the leakage of current from the operating equipment.

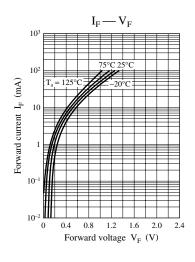
2. Rated input/output frequency: 2 GHz

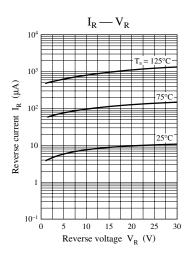
3. \*: t<sub>rr</sub> measuring instrument

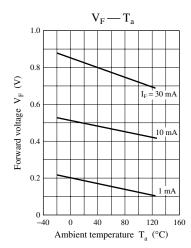


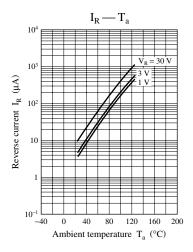


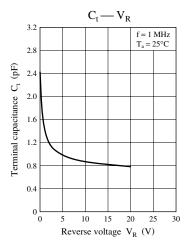
Note) The part number in the parenthesis shows conventional part number.











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